Amendments to the Specification

Please replace the paragraph [0007] with the following rewritten paragraph:

[0007] Although generally effective, this conventional interposer socket arrangement does have at least one shortcoming. As the size of the electrical components being retained by such socket increases, the number of bumps increases as well. It is not uncommon today to have a microprocessor package designed for interposer mounting that has 1443 bumps. Because each bump still must have the pre-determined amount of compressive force (*e.g.*, 100 grams per bump), the total amount of compressive force on the chip has become quite large requiring hundreds of pounds of total force. An increase in force can be achieved through the use of stiffer springs 18 (having a larger spring constant). Turning the screws 16~~4~~0 under such large total force occasionally can cause conditions known as galling and/or "cold welding." This condition has to do with the friction between the threads of the screws 16~~4~~0 and the corresponding threads of the posts 20. As the total force increases with the use of stiffer springs, the friction increases and, in a relatively small percentage of cases, actually can cause the screw 16~~4~~0 to become welded to the post 20 preventing the screw from being turned further, preventing sufficient force to be applied to the component and perhaps causing the screw to break. Also, metallic particles can be created when the screws are tightened which can short some of the contacts and cause damage to the chip.